

CLAIMS

1. An internal conductor connection structure characterized by connecting at least two via conductors adjacent to each other at a predetermined interval in an insulator substrate and line conductors disposed in the insulator substrate, wherein one of the via conductors includes a continuous via conductor disposed extending in a direction farther from the other via conductor, and the one of the via conductors is connected to the line conductor through the continuous via conductor.

2. The internal conductor connection structure according to Claim 1, characterized in that a connecting portion of the line conductor to the continuous via conductor or a connecting portion of the continuous via conductor to the line conductor is disposed as a connecting land having an area larger than a connecting portion of the counterpart.

3. A multilayer substrate characterized by comprising a laminate in which a plurality of insulator layers are laminated, at least first and second via conductors individually extending inside the laminate from positions adjacent to each other at a predetermined interval on one of main surfaces of the laminate, and a first line conductor connected to the first via conductor, wherein the first via conductor includes a first continuous via conductor disposed extending in a direction farther from the second via conductor, and the first via conductor is connected to the first line conductor through the first continuous via conductor.

4. The multilayer substrate according to Claim 3, characterized by further comprising a third via conductor at predetermined distances from the first and second via conductors, the third via conductor

extending inside the laminate from the one of main surfaces of the laminate, wherein the second via conductor includes a second continuous via conductor disposed extending in a direction farther from both the first and third via conductors, and the second via conductor is connected to a second conductor line through the second continuous via conductor.

5. The multilayer substrate according to Claim 4, characterized in that the first continuous via conductor and the second continuous via conductor are disposed in their respective insulator layers different from each other.

6. The multilayer substrate according to Claim 4 or Claim 5, characterized in that the first continuous via conductor and the second continuous via conductor are disposed in their respective insulator layers thinner than other insulator layers.

7. The multilayer substrate according to any one of Claim 4 to Claim 6, characterized in that the first continuous via conductor and the second continuous via conductor penetrate their respective insulator layers.

8. The multilayer substrate according to any one of Claim 4 to Claim 6, characterized in that the first continuous via conductor and the second continuous via conductor do not penetrate their respective insulator layers.

9. The multilayer substrate according to any one of Claim 3 to Claim 8, characterized in that a connecting portion of the first line conductor to the first continuous via conductor or a connecting portion of the first continuous via conductor to the first line

conductor is disposed as a connecting land larger than a connecting portion of the counterpart.

10. The multilayer substrate according to any one of Claim 4 to Claim 9, characterized in that a connecting portion of the second continuous via conductor to the second line conductor or a connecting portion of the second line conductor to the second continuous via conductor is disposed as a connecting land larger than a connecting portion of the counterpart.

11. The multilayer substrate according to any one of Claim 3 to Claim 10, characterized in that a surface electrode connected to each of the via conductors is disposed on the one of main surfaces.

12. The multilayer substrate according to any one of Claim 3 to Claim 10, characterized in that an electronic component is mounted on the one of main surfaces, and external terminal electrodes of this electronic component are connected to the first via conductor and the second via conductor exposed at the main surface, without through any surface electrode.

13. The multilayer substrate according to any one of Claim 3 to Claim 12, characterized in that the one main surface side is configured to be connectable to a mother board.

14. The multilayer substrate according to any one of Claim 3 to Claim 13, characterized in that the insulator layer comprises a low-temperature sinterable ceramic material.

15. The multilayer substrate according to any one of Claim 3 to Claim 14, characterized in that each of the via conductors and the

line conductors is individually comprises an electrically conductive material primarily containing silver or copper.